

AMENDMENTS

Amendments to the Specification

Please replace the section on page 1 titled, "Related Applications" with the following replacement section, marked up to show all changes relative to the previous version of the section:

Related Applications

This application is a continuation in part of U.S.S.N. 09/289,036 filed on April 9, 1999 and issued on February 11, 2003 as U.S. Patent No. 6,518,949, and claims priority to provisional applications U.S.S.N. 60/144,943 filed on July 21, 1999 and U.S.S.N. 60/147,989 filed on August 10, 1999, the entire contents of which are incorporated herein by reference.

Please replace the section on page 32 titled, "Abstract of the Invention" with the following replacement section, marked up to show all changes relative to the previous version of the section:

Abstract of the Invention

In one embodiment of the invention, a method of manufacturing a semiconductor device comprises the steps of: a) providing an organic semiconductor layer; b) depositing a reactive species on a portion of the organic semiconductor layer; and c) reacting the reactive species with the portion of the organic layer to form a dielectric layer. ~~In another embodiment, a method of manufacturing a semiconductor device comprises the steps of: a) providing an organic semiconductor layer; and b) exposing a surface of the organic semiconductor layer to a radiation to form a dielectric layer. In another embodiment, a method of manufacturing a transistor comprises the steps of: a) providing an organic semiconductor layer adjacent a gate electrode; b) providing an electrochemical cell wherein the gate electrode is an electrode of the electrochemical cell; and c) applying a voltage to the gate electrode to cause an electrochemical reaction to form a gate dielectric between~~

~~the gate electrode and the organic semiconductor layer. In one embodiment, a method of protecting organic layers in an electronic device, comprises the steps of: a) providing a first organic layer; b) providing a barrier layer adjacent to the first organic layer, wherein the barrier layer is resistant to a solvent; and c) providing a solution or a dispersion comprising the solvent and a layer-forming material adjacent to the first organic layer.~~